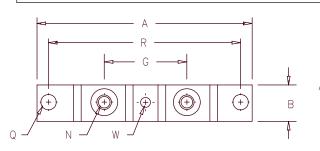
Schottky PowerMod





Baseplate A=Common Anode





Baseplate Common Cathode

Baseplate

D=Doubler

Notes: Baseplate: Nickel plated copper

Dim. Inches		Millimeters		
Min.	Max.	Min.	Max.	Notes
A B 0.700 C E 0.120 F 0.490 G 1.375 H 0.050 N Q 0.275 R 3.150 U 0.600 V 0.312 W 0.180	0.510 BSC 0.290 0 BSC 	12.45 34.92 1.25 6.99 80.0 15.24 7.92	7.37 1 BSC	1/4-20 Dia.

Microsemi	Industry	Working Peak	Repetitive Peak
Catalog Number	Part Number	Reverse Voltage	Reverse Voltage
CPT50080* CPT50090* CPT500100*	MBR50080CT MBR500100CT	80V 90V 100V	80V 90V 100V

*Add Suffix A for Common Anode, D for Doubler

- Schottky Barrier Rectifier
- Guard ring protection
- 500 Amperes / 80 to 100 Volts
- 175°C junction temperature
- Reverse energy tested
- ROHS Compliant

Electrical Characteristics

F(AV) 500 Amps Average forward current per pkg Average forward current per leg Maximum surge current per leg Maximum repetitive reverse current per leg | R(OV) 2 Amps Max peak forward voltage per leg | VFM 0.90 Vol Max peak forward voltage per leg Max peak forward voltage per leg Max peak reverse current per leg Max peak reverse current per leg C_{J} Typical junction capacitance per leg

F(AV) 250 Amps IFSM 5000 Amps 0.90 Volts V_{FM} 0.72 Volts ^IRM 200 mA ^IRM 8.0 mA 6400 pF

 ^{T}C = 122°C, Square wave, $^{R}\Theta JC$ = 0.12°C/W ^{T}C = 122°C, Square wave, $^{R}\Theta JC$ = 0.24°C/W 8.3ms, half sine, \overline{J} = 175°C f = 1 KHZ, 25°C, 1 μ sec square wave \overline{J} = 250A: \overline{J} J = 25°C

TFM = 250A:TJ = 175°C VRRM,TJ = 125°C* VRRM,TJ = 25°C $V_R = 5.0V, T_C = 25^{\circ}C$

*Pulse test: Pulse width 300 µsec, Duty cycle 2%

Thermal and Mechanical Characteristics

TSTG Storage temp range -55℃ to 175℃ ΤJ Operating junction temp range -55℃ to 175℃ R OJC 0.24°C/W Junction to case Max thermal resistance per leg $\mathsf{R} \; \mathsf{\Theta} \mathsf{J} \mathsf{C}$ 0.12°C/W Max thermal resistance per pkg Junction to case Recs 0.08°C/W Case to sink Typical thermal resistance (greased) 35-40 inch pounds Terminal Torque Mounting Base Torque (outside holes) Mounting Base Torque (center hole) 30-40 inch pounds 8-10 inch pounds center hole must be torqued first 2.8 ounces (78 grams) typical Weight



CPT50080 - CPT500100

Typical Forward Characteristics — Per Leg

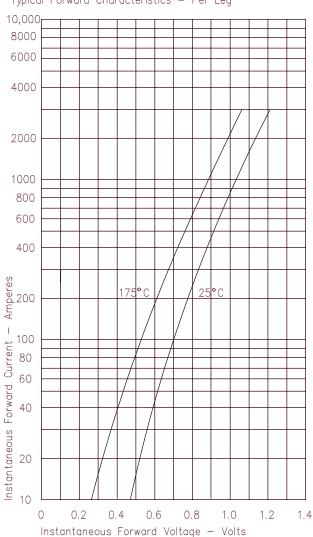


Figure 3 Typical Junction Capacitance - Per Leg 100,000 60,000 40,000 20,000 Junction Capacitance 10,000 6000 4000 2000 1000 0.1 0.5 1.0 5.0 10 50 100

Figure 4

Forward Current Derating — Per Leg

Reverse Voltage - Volts



Figure 2 Typical Reverse Characteristics — Per Leg

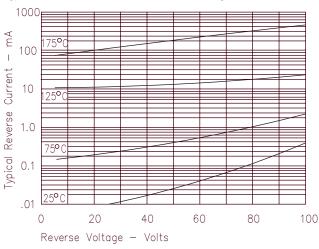
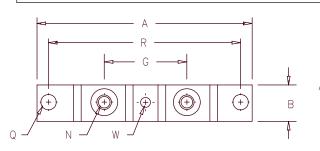


Figure 5
Maximum Forward Power Dissipation — Per Leg





Schottky PowerMod





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Baseplate

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CPT50080 - CPT500100

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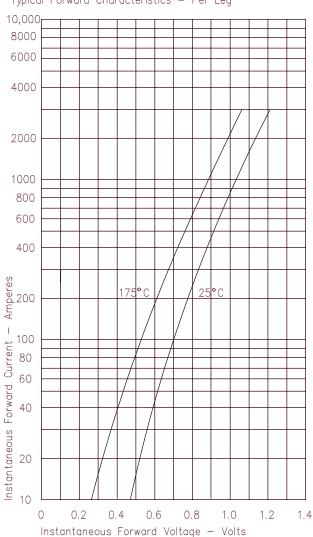


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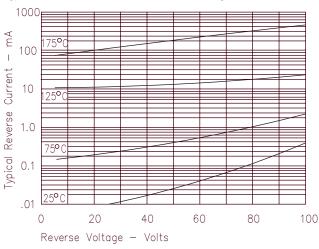


Figure 5
Maximum Forward Power Dissipation — Per Leg





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